

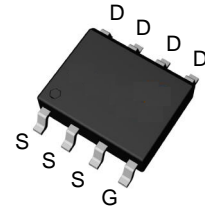
Features

- 30V/20 A,
 $R_{DS(ON)} = 3.2\text{m}\Omega(\text{typ.}) @ V_{GS} = 10\text{V}$
 $R_{DS(ON)} = 5\text{m}\Omega(\text{typ.}) @ V_{GS} = 4.5\text{V}$
- Lower Q_g and Q_{gd} for high-speed switching
- Lower $R_{DS(ON)}$ to Minimize Conduction Losses
- Reliable and Rugged
- Lead Free and Green Devices Available
 (RoHS Compliant)

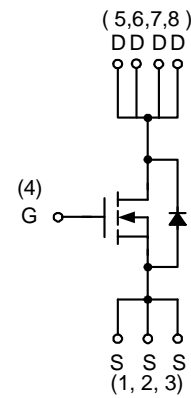
Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems.

Pin Description



Top View of SOP8



N-Channel MOSFET

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
Common Ratings ($T_A=25^\circ\text{C}$ Unless Otherwise Noted)			
V_{DSS}	Drain-Source Voltage	30	V
V_{GSS}	Gate-Source Voltage	± 20	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	
I_S	Diode Continuous Forward Current	$T_A=25^\circ\text{C}$ 2	A
I_D	Continuous Drain Current	$T_A=25^\circ\text{C}$ 20	
		$T_A=70^\circ\text{C}$ 15.4	
I_{DM}^a	Pulsed Drain Current	$T_A=25^\circ\text{C}$ 37	
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$ 1.6	W
		$T_A=70^\circ\text{C}$ 1.02	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	$t \leq 10s^b$ 32	$^\circ\text{C/W}$
		Steady State ^c 78	
$R_{\theta JL}$	Thermal Resistance-Junction to Lead	Steady State 20	
I_{AS}^d	Avalanche Current, Single pulse ($L=0.1\text{mH}$)	29	A
E_{AS}^d	Avalanche Energy, Single pulse ($L=0.1\text{mH}$)	42	mJ

Note a: Pulse width limited by max. junction temperature.

b: $t \leq 10s$ and surface mounted on FR-4 board using 1in2 pad, 2 oz Cu.

c: Steady time = 999s and surface mounted on FR-4 board using 1in2 pad, 2 oz Cu.

d: UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature $T_J=25^\circ\text{C}$).

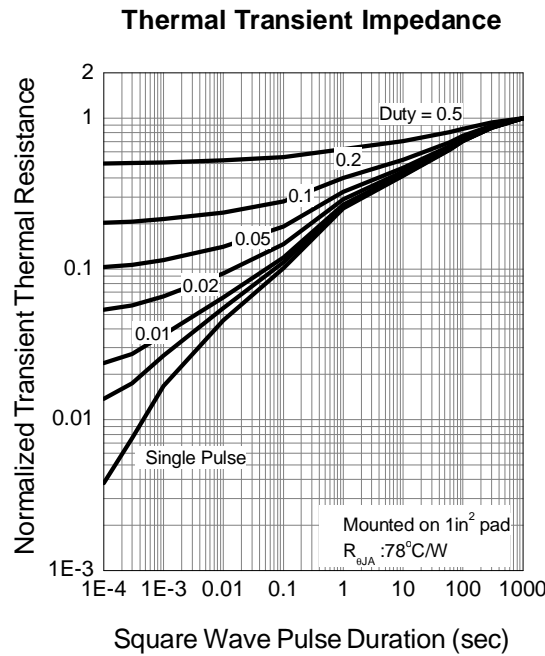
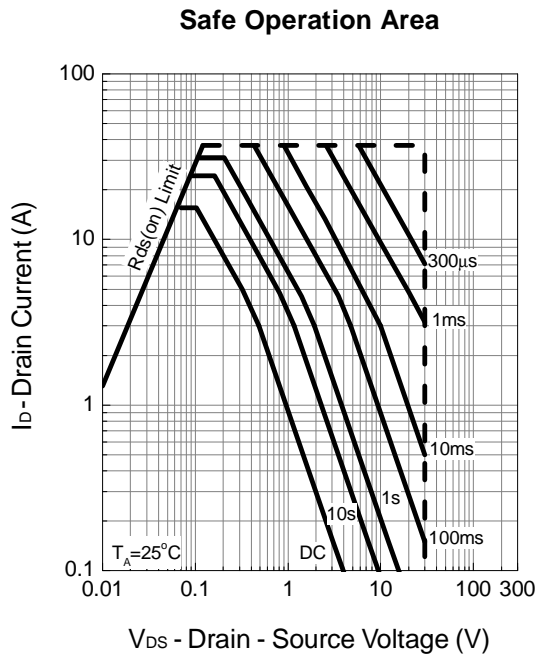
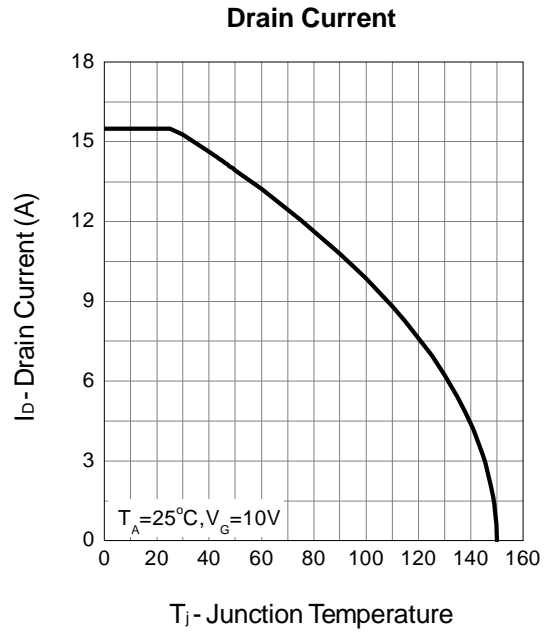
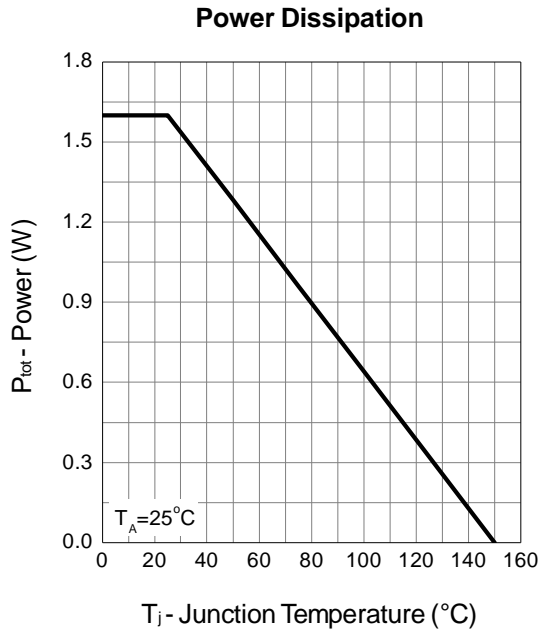
Electrical Characteristics ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	30	-	-	V
$BV_{DSS(t)}$	Drain-Source Breakdown Voltage (transient)	$V_{GS}=0V, I_{D(aval)}=29A$ $T_{case}=25^\circ C, t_{transient}=100ns$	34	-	-	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=24V, V_{GS}=0V$	-	-	1	μA
		$T_J=85^\circ C$	-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	1.4	1.7	2.5	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
$R_{DS(on)}^e$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=13A$	-	3.2	4.4	m Ω
		$V_{GS}=4.5V, I_{DS}=9A$	-	5.0	6.8	
Gfs	Forward Transconductance	$V_{DS}=7.6, I_D=8A$	-	22	-	S
Diode Characteristics						
V_{SD}^e	Diode Forward Voltage	$I_{SD}=10A, V_{GS}=0V$	-	0.78	1.1	V
t_{rr}	Reverse Recovery Time	$I_{sd}=13A, di_{SD}/dt=100A/\mu s$	-	52	-	ns
Q_{rr}	Reverse Recovery Charge	$V_{DD}=15V,$	-	30	-	nC
Dynamic Characteristics^f						
R_G	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	-	1.1	2	Ω
C_{iss}	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=15V,$ Frequency=1.0MHz	-	1600	1990	pF
C_{oss}	Output Capacitance		-	900	-	
C_{riss}	Reverse Transfer Capacitance		-	65	85	
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=15V, R_L=15\Omega,$ $I_{DS}=1A, V_{GEN}=10V,$ $R_G=1\Omega$	-	13.6	-	ns
t_r	Turn-on Rise Time		-	12.6	-	
$t_{d(OFF)}$	Turn-off Delay Time		-	24.4	-	
t_f	Turn-off Fall Time		-	38.4	-	
Gate Charge Characteristics^f						
Q_g	Total Gate Charge	$V_{DS}=15V, V_{GS}=10V,$ $I_{DS}=13A$	-	19.4	26	nC
Q_g	Total Gate Charge	$V_{DS}=15V, V_{GS}=4.5V,$ $I_{DS}=13A$	-	9.4	-	
Q_{gs}	Gate-Source Charge		-	3.9	-	
Q_{gd}	Gate-Drain Charge		-	2.2	-	
Q_{gth}	Threshold Gate Charge		-	2.1	-	

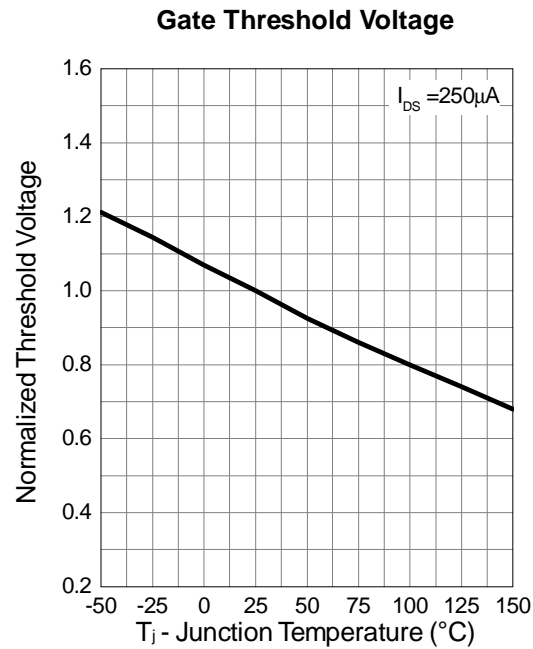
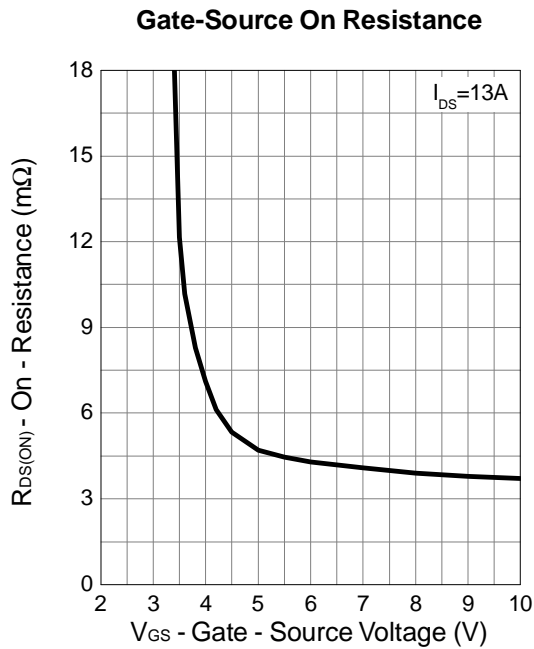
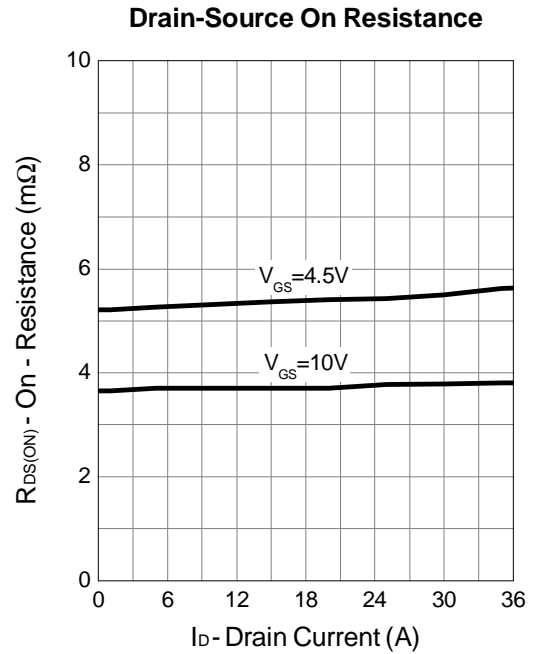
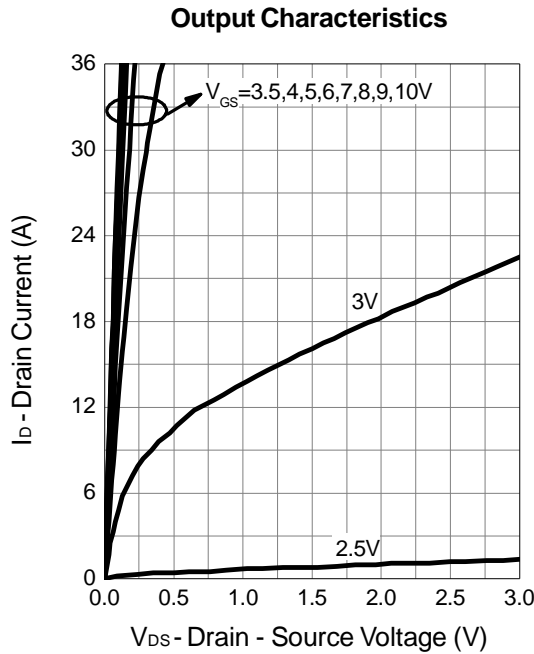
 Note e: Pulse test. Pulse width $\leq 300 \mu s$, duty cycle $\leq 2\%$.

f: Guaranteed by design, not subject to production testing.

Typical Operating Characteristics

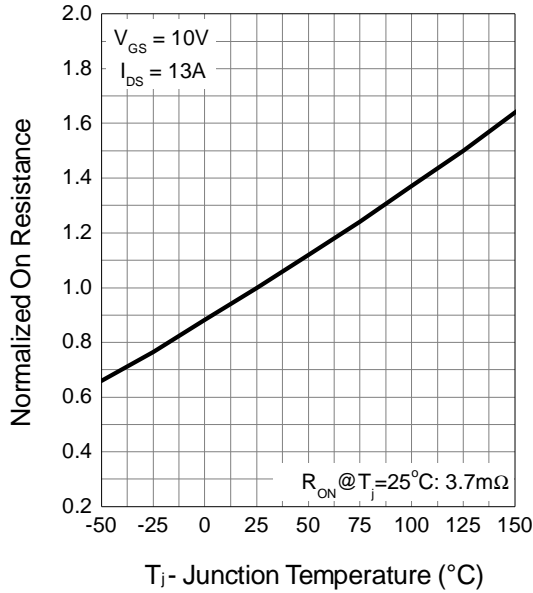


Typical Operating Characteristics (Cont.)

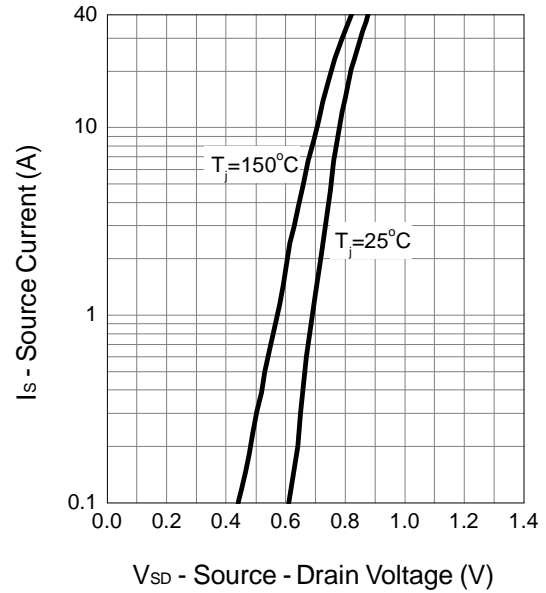


Typical Operating Characteristics (Cont.)

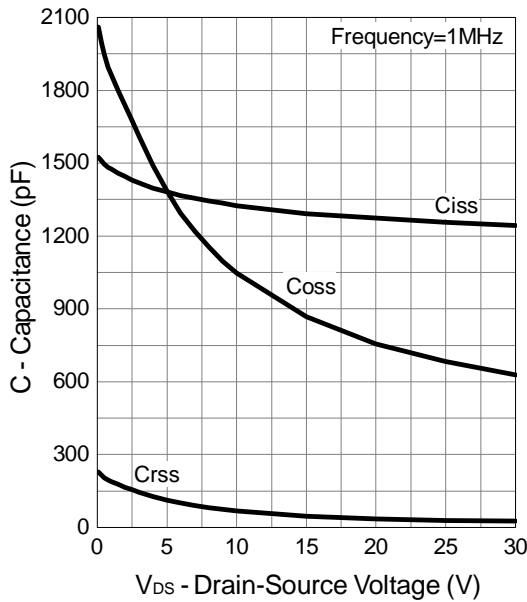
Drain-Source On Resistance



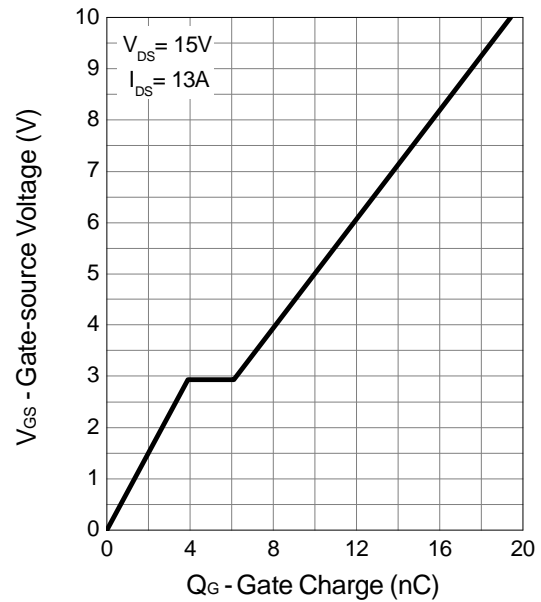
Source-Drain Diode Forward



Capacitance

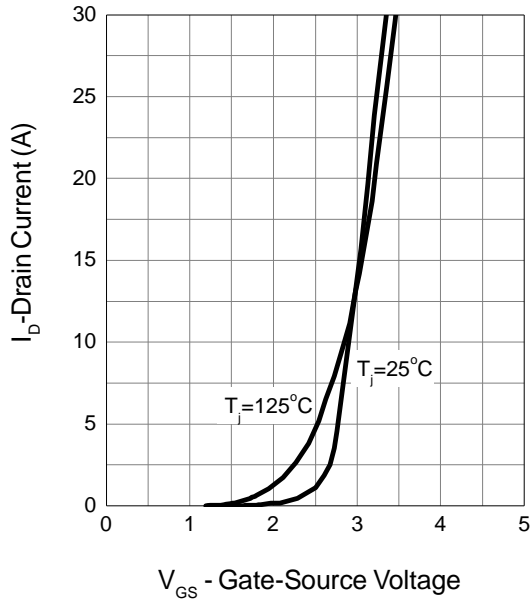


Gate Charge

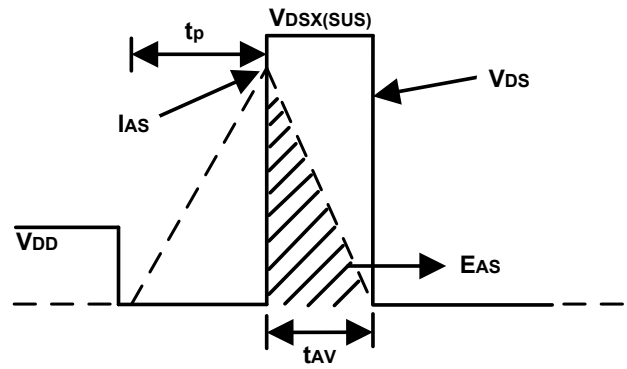
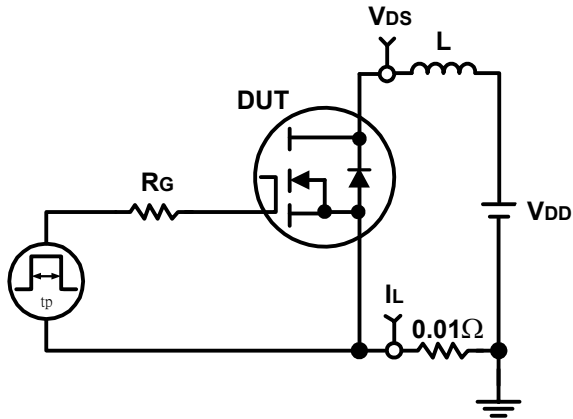


Typical Operating Characteristics (Cont.)

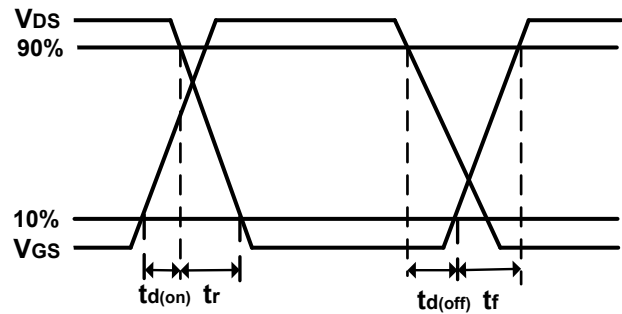
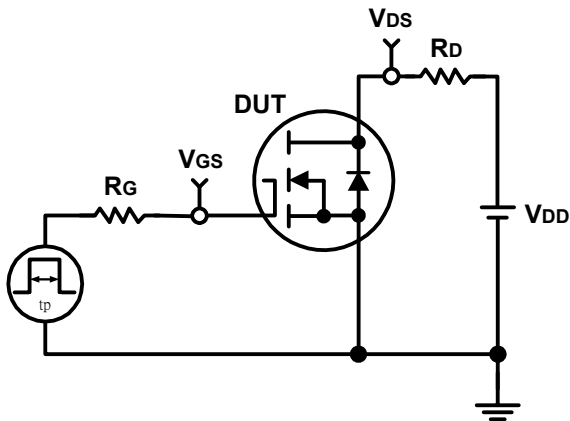
Transfer Characteristics



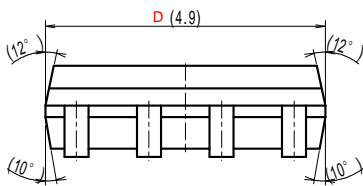
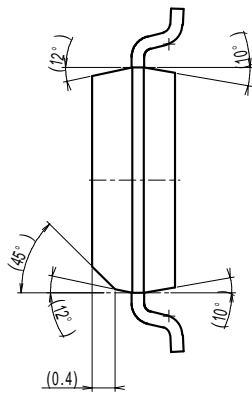
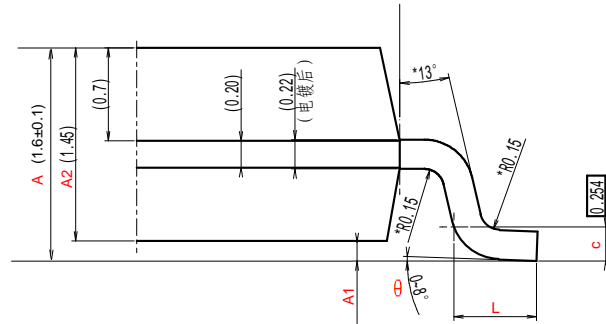
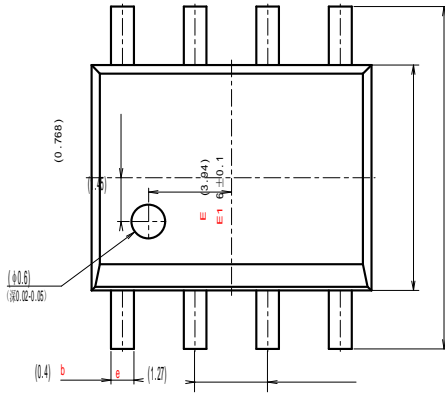
Avalanche Test Circuit and Waveforms



Switching Time Test Circuit and Waveforms



SOP8 PACKAGE OUTLINE



字符	Dimension millimeters		
	Min	Standard	Max
A	1.500	1.600	1.700
A1	0.040	0.080	0.150
A2	1.350	1.450	1.550
b	0.300	0.400	0.500
c	0.220	0.254	0.280
D	4.800	4.900	5.000
E	3.840	3.940	4.040
E1	5.900	6.000	6.100
e		1.27 (BSC)	
L	0.400	0.550	0.700
θ	0°		8°